

Title (en)

MANUFACTURING METHOD OF TRANSFORMER CIRCUIT BOARD AND TRANSFORMER THEREOF

Title (de)

HERSTELLUNGSVERFAHREN FÜR TRANSFORMATORLEITERPLATTE UND TRANSFORMATOR DAMIT

Title (fr)

PROCÉDÉ DE FABRICATION DE CARTE DE CIRCUIT DE TRANSFORMATEUR ET TRANSFORMATEUR ASSOCIÉ

Publication

EP 3675144 A1 20200701 (EN)

Application

EP 18215834 A 20181224

Priority

EP 18215834 A 20181224

Abstract (en)

A manufacturing method of transformer circuit board (100) includes following steps: plate stamping (S1), forming a plurality of metal plates (10) with a stamping mold; primary layering (S2), layering the metal plates (10) that are in alignment with each other between two outer insulation layers (20), with an inner insulation layer (21) disposed between the two metal plates (10); primary pressing (S3), hot pressing the metal plates (10) to fix the metal plates (10) between the two outer insulation layers (20); secondary layering (S4), layering another metal plate (10) on the outer side of the two outer insulation layers (20), respectively, corresponding to the positions of the previously layered metal plates (10); secondary pressing (S5), hot pressing the metal plates (10) on the outer side of the outer insulation layers (20), and printing to form a solder mask layer (30) on the outer insulation layers (20). Finally, cutting to form a transformer circuit board (100) with low leakage inductance and high EMI shield.

IPC 8 full level

H01F 27/28 (2006.01)

CPC (source: EP)

H01F 27/28 (2013.01)

Citation (search report)

- [XAI] US 2017027061 A1 20170126 - LIN CHUN-CHIH [TW], et al
- [XAI] CN 101599347 B 20110406 - BEIJING KENNETT SCIENCE & TECHNOLOGY CO LTD
- [A] WO 9959170 A1 19991118 - NIDEC AMERICA CORP [US]
- [A] US 2005270745 A1 20051208 - CHEN KANGHUA [US], et al

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

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